

FEATURES

- | 35 Watts Peak Pulse Power per Line (tp=8/20μs)
- | Protects one bidirectional I/O line
- | Working voltages : 18 V
- | Ultra Low leakage current

APPLICATIONS

- | Smart phones
- | Display Ports
- | MDDI Ports
- | USB Ports
- | Digital Video Interface (DVI)
- | PCI Express and Serial SATA Port



DFN1006

18B

Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±15kV (air), ±15kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- | | |
|-------------|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |



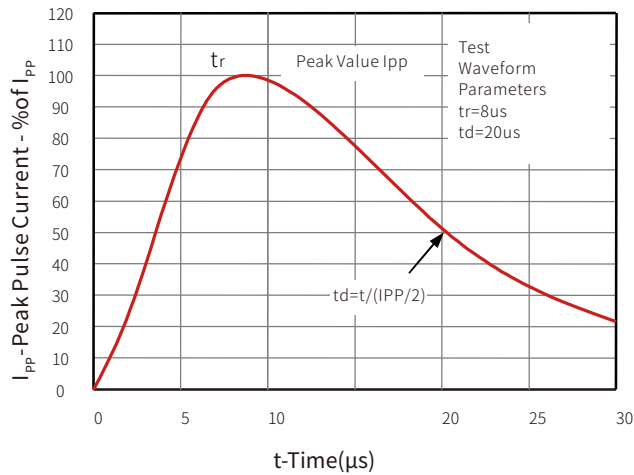
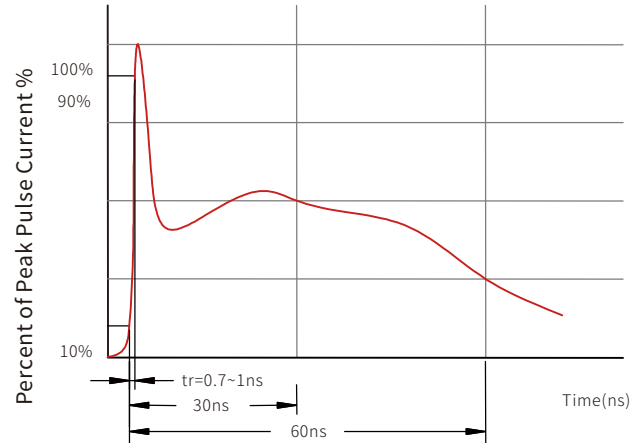
Schematic Symbol

THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{pp}	Peak Pulse Power (tp=8/20μs waveform)	35	Watts
T_J	Operating Temperature Range	-55 to +150	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

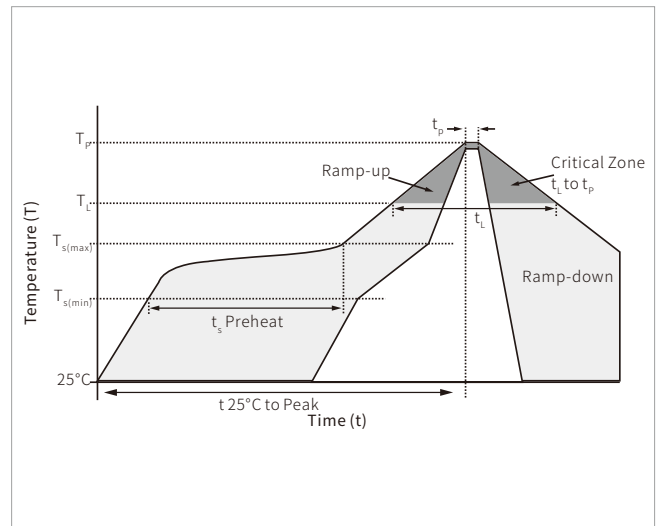
ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				18	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	19	22		V
I_R	Reverse Leakage Current	$V_{RWM}=18V$			1	μA
V_C	Clamping Voltage	$I_{pp}=1A, tp=8/20\mu s$		4		V
V_C	Clamping Voltage	$I_{pp}=5A, tp=8/20\mu s$		6	8	V
V_C	Clamping Voltage	$I_{pp}=16A, (ESD=8KV)$		8.2		V
I_{pp}	Peak Pulse Current	$tp=8/20\mu s$			5	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$		0.5	0.7	pF

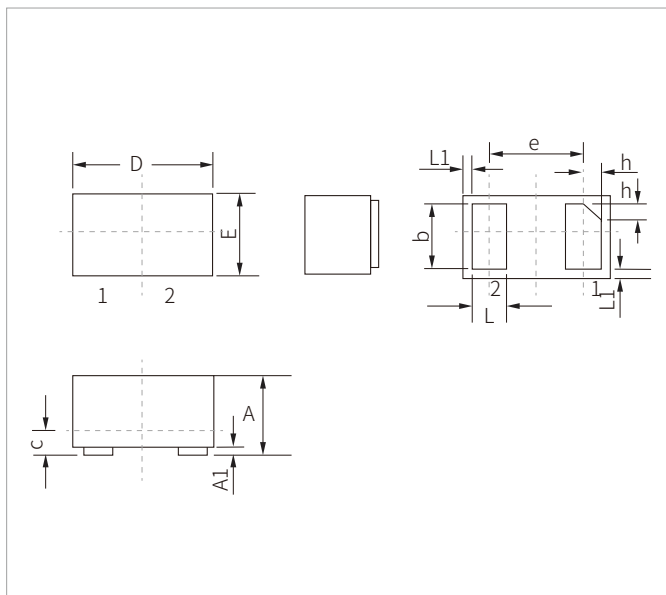
8/20 μ s Pulse Waveform

ESD Pulse Waveform (according to IEC 61000-4-2)


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

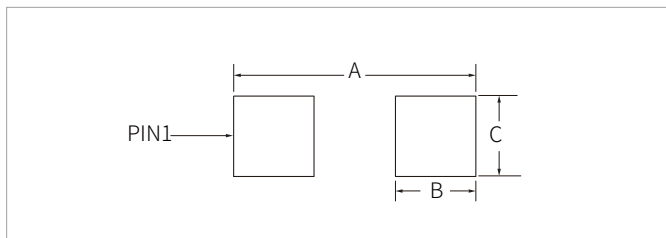


DFN1006 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.40	0.60	0.016	0.024
A1	0	0.05	0	0.002
b	0.40	0.55	0.016	0.022
c	0.12	0.18	0.005	0.007
D	0.90	1.10	0.035	0.043
e	0.65BSC		0.026BSC	
E	0.55	0.75	0.022	0.030
L	0.20	0.35	0.008	0.014
L1	0.05REF		0.002REF	
h	0.07	0.17	0.003	0.007

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	1.20	0.047
B	0.47	0.019
C	0.60	0.024

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE10F04B18MA-SP	DFN1006	10000PCS	7"

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